/ Descriptions

SOT23-6 P

P- CHANNEL MOSFET in a SOT23 -6 Plastic Package.

ψ /

V_{DS}=-60V; I_D=-3A

$R_{DS(on)1}$@-10V ≤ 100mΩ(Type.83mΩ)

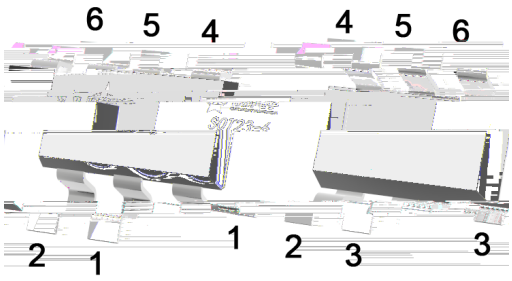
$R_{DS(on)2}$@-4.5V ≤ 130mΩ(Type.100mΩ)

HF Product.

PWM

PWM application & Load switch.

/ Equivalent Circuit



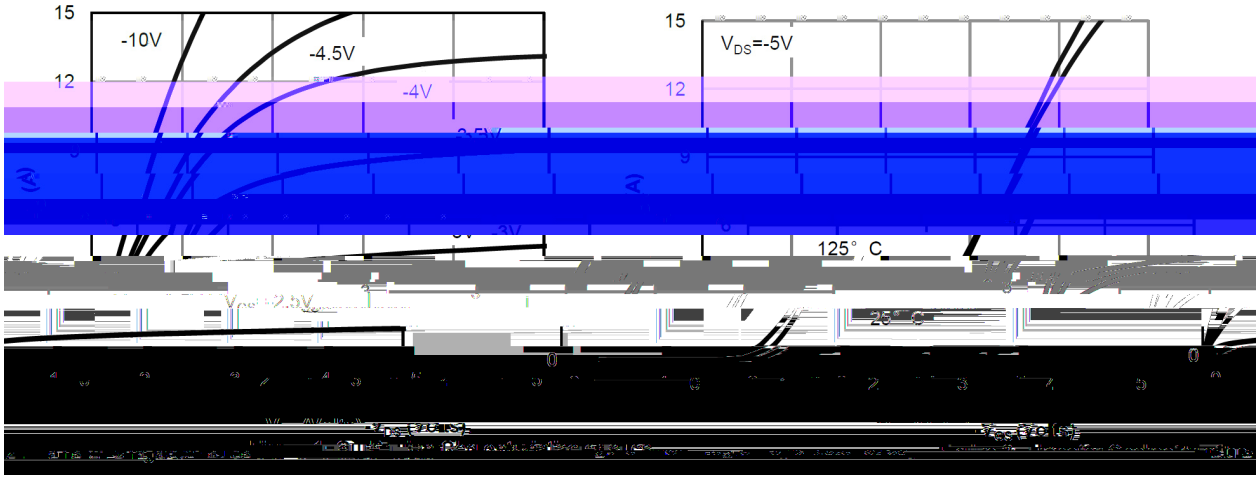
PIN1 D PIN 2 D PIN 3 G PIN 4 S PIN 5 D PIN 6 D

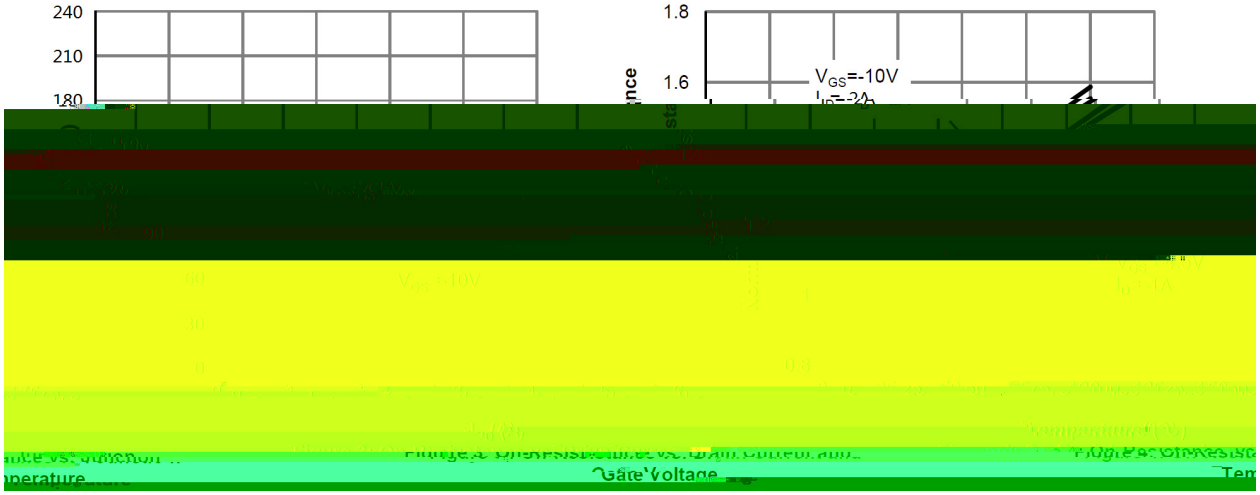
/ Marking

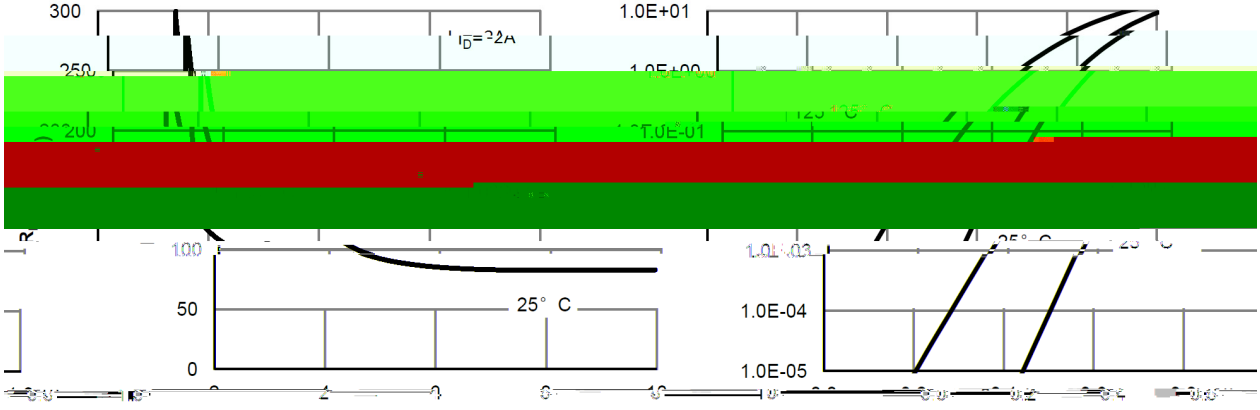
See Marking Instructions.

Parameter	Symbol	Rating	Unit
Drain–Source Voltage	V_{DSS}	-60	V
Gate–Body Leakage Voltage	V_{GSS}	±20	V
Drain Current – Continuous	I_D	-3	A
Pulsed Drain Current	I_{DM}	-16	A
Power Dissipation	P_D	1.4	W

/ Electrical Characteristic Curve







$-V_{GS}$ (Volts)
Figure 5: On-Resistance vs. Gate-Source Voltage

$-V_{SD}$ (Volts)
Figure 6: Body-Diode Charact

/ Electrical Characteristic Curve

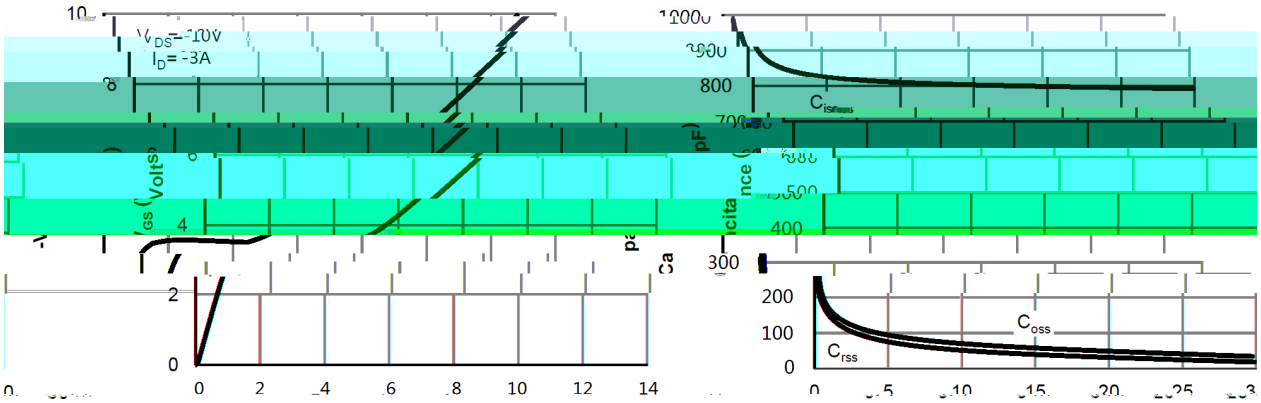
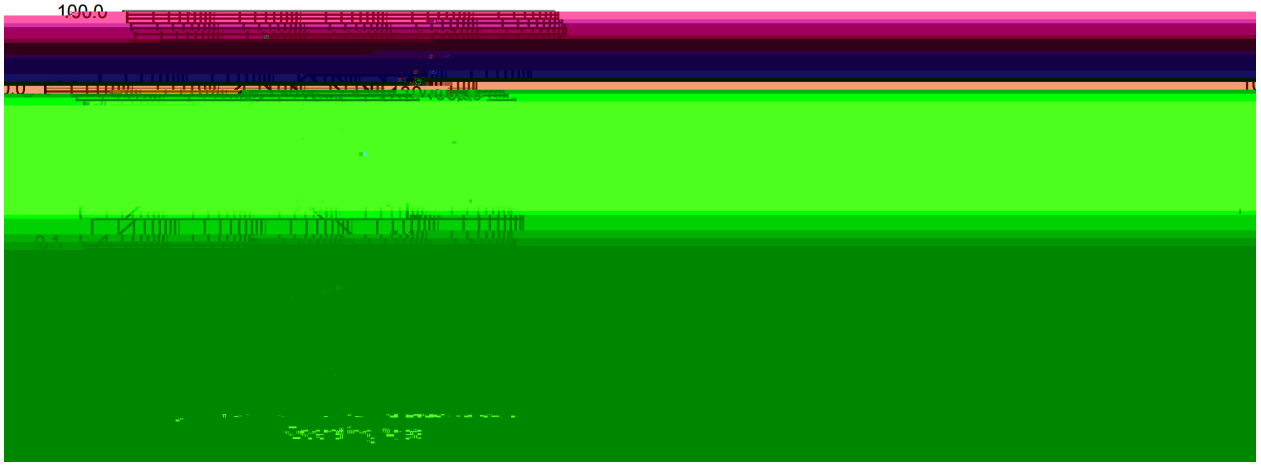
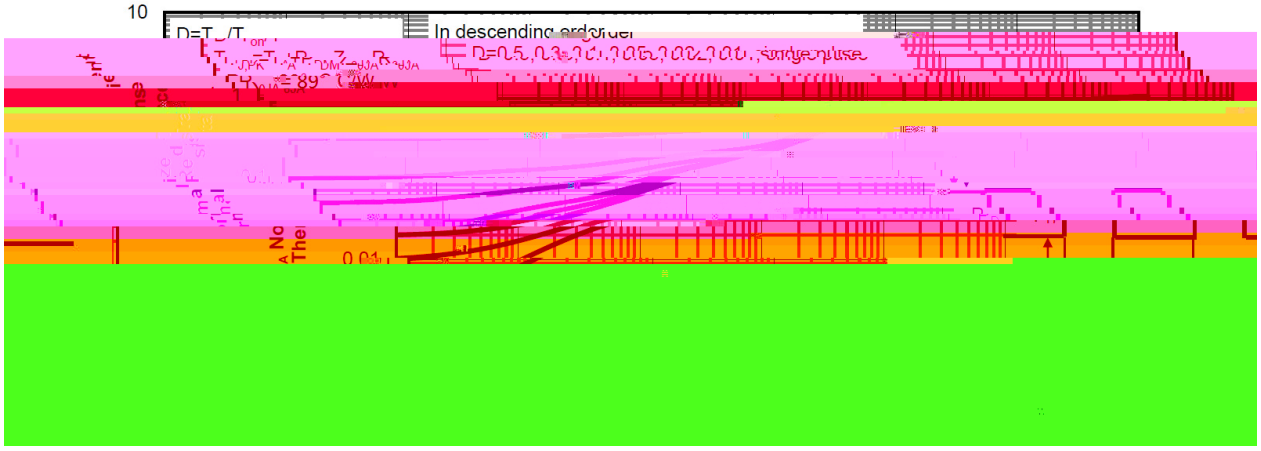


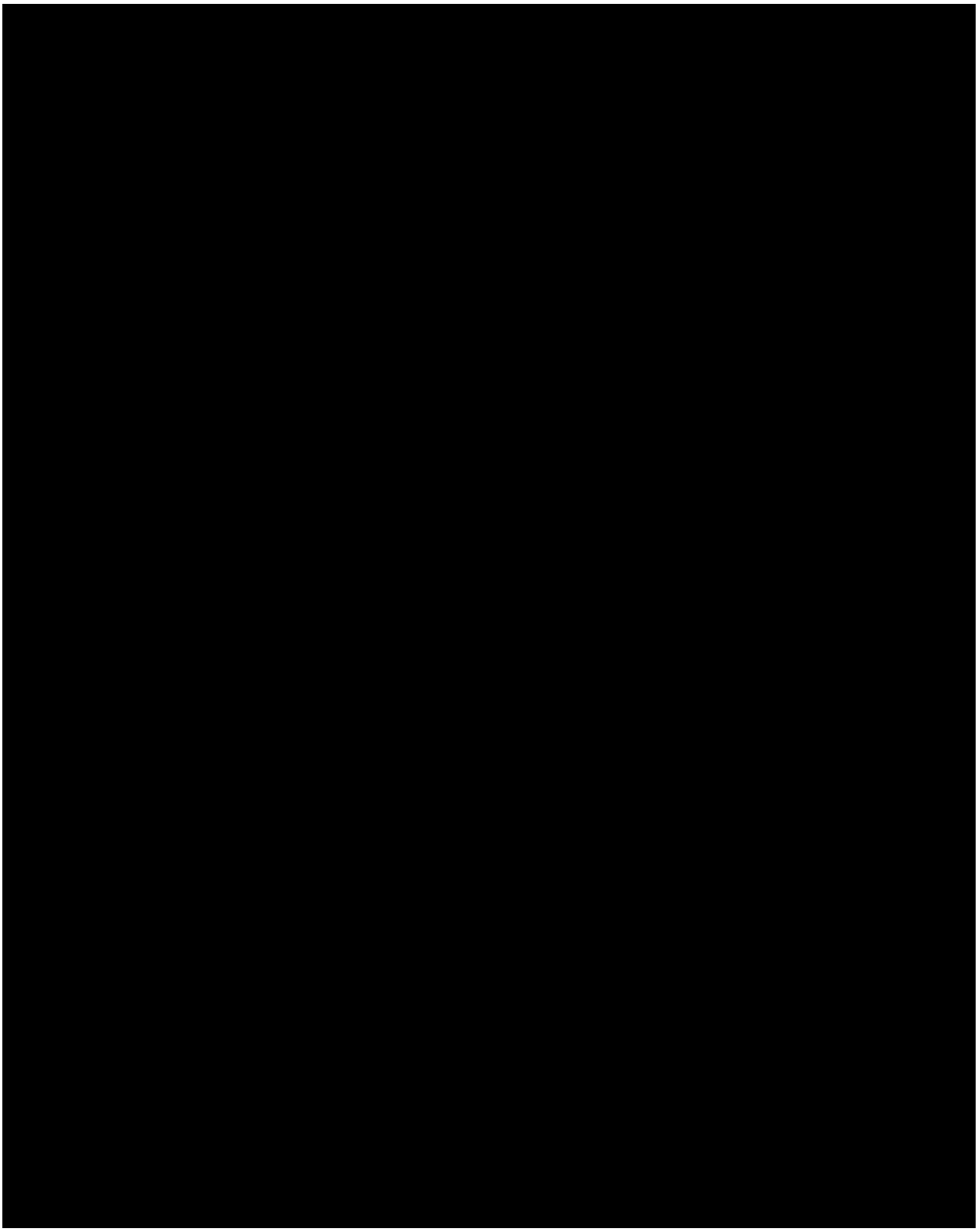
Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

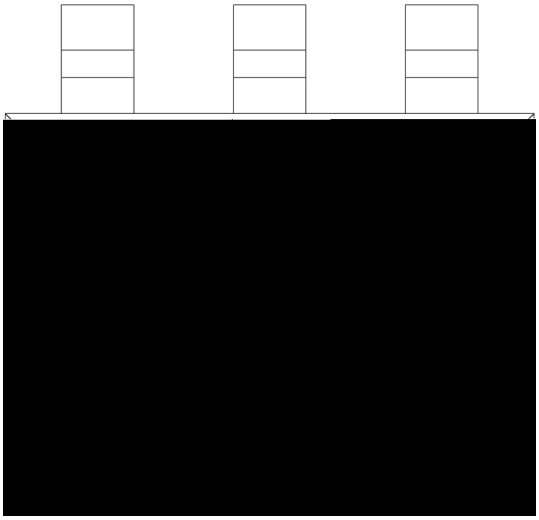




/ Package Dimensions



/ Marking Instructions



C1:

H

****:

Note:

C1:	Product Type Code
H:	Company Code
****	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

				Note:
1	150	180	60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5		5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3		2 10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension	(unit mm³)